

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6479254

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BEIJING MICRO-ELECTRONICS OF CAS INVESTMENT CO. LTD	12/21/2020
RECEIVING PARTY DATA	
Name:	ZHONGKE FUTURE OF CHIP MICROELECTRONICS TECHNOLOGY CHENGDU CO. LTD
Street Address:	BUILDING 1#, CHANGDU IC VALLEY RESEARCH AND INNOVATION CENTER,
Internal Address:	NO. 388, GUOXIN AVENUE, SHUANGLIU DISTRICT
City:	CHENGDU
State/Country:	CHINA
Postal Code:	610299
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14412408
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	SUN28-40027
NAME OF SUBMITTER:	PATRICE DAY
SIGNATURE:	/Patrice Day/
DATE SIGNED:	01/05/2021
Total Attachments: 3	
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PATENT ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Beijing Micro-electronics of CAS Investment Co. Ltd., a Chinese corporation (“Assignor”) has sold, assigned, transferred, and conveyed, and by these presents hereby irrevocably sells, assigns, transfers and conveys unto:

Assignee’s Name: Zhongke Future of Chip Microelectronics Technology Chengdu Co.ltd
Assignee’s Address: Building 1#, Chengdu IC Valley Research and Innovation Center, No.388, Guoxin Avenue, Shuangliu District, Chengdu, 610299, China

(hereinafter “Assignee”) the entire right, title and interest throughout the world and without geographic restriction, in and to:

- (a)
 - (i) the patents and patent applications set forth on the attached [**Schedule 1**];
 - (ii) all patents that issue from any patent applications on [**Schedule 1**];
 - (iii) all continuations, continuations-in-part, divisionals, extensions, substitutions, reissues, re-examinations and renewals, of any patent or patent application described in the preceding subclauses (i) and (ii);
 - (iv) any patents or patent applications from which any items described in the preceding subclauses (i) through (iii) claim priority or that claim priority from any of them; and
 - (v) all inventions disclosed in any items described in the preceding subclauses (i) through (iv) (all items described in this clause (a) is collectively, the “Patents”);
- (b) all rights of any kind accruing under any of the Patents provided by all applicable law of any jurisdiction anywhere in the world and by all international treaties and conventions throughout the world;
- (c) all rights to any royalties, fees, income, payments, and other proceeds now or hereafter due or payable arising from or relating to any Patents or rights described in the preceding clauses (a) and (b); and
- (d) all claims and causes of action arising from or relating to any Patents or rights described in the preceding clauses (a), (b), or (c), whether accruing before, on, or after the date of this Agreement, including all rights to and claims for damages, restitution, and injunctive and other legal and equitable relief for past, present, and future infringement, misappropriation,

violation, misuse, breach or default, with the right but no obligation to sue for such legal and equitable relief and to collect, or otherwise recover, any such damages.

By virtue of this Assignment, all of the Assignor's interests in the foregoing properties are to be owned by said Assignee, its successors and assigns, to the full end of the term or terms for which any such Patents may be granted, as fully and entirely as would have been held and enjoyed by Assignor had this Assignment not been made.

The Assignor represents, warrants, covenants, and agrees that the Assignor has the full and unencumbered right to sell, assign, transfer, and convey the interests herein sold, assigned, transferred, and conveyed, and that the Assignor has not executed and will not execute any document or instrument in conflict herewith.

The Assignor hereby grants the firm of **Taft Stettinius Hollister LLP**, or any attorney thereof that is a registered practitioner before U.S. Patent and Trademark Office, the power to insert into this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office concerning recordation of this Assignment.

IN WITNESS WHEREOF, Assignor has duly executed and delivered this Patent Assignment as of the date first written above.

[ASSIGNOR]

[ASSIGNEE]

By: Liwei Shang

By: Wang Yunfeng

Name: Shang Liwei

Name: Wang Yunfeng

Title: General Manager

Title: General Manager

Date: December 21, 2020

Date: December 21, 2020

SCHEDULE 1

Assigned Patents and Patent Applications

Active U.S. Patents:

Patent No.	Application Date	Patent Title	Expiration Date
US2013 14412404	01/21/2013	STRUCTURE AND FABRICATION METHOD OF A HIGH PERFORMANCE MEMS THERMOPILE IR DETECTOR	
US2013 14412408	01/21/2013	BLACK SILICON-BASED HIGH-PERFORMANCE MEMS THERMOPILE IR DETECTOR AND FABRICATION METHOD	